

OWLS: A Mixed-Signal ASIC for Optical Wire-Less Links In Space Instruments

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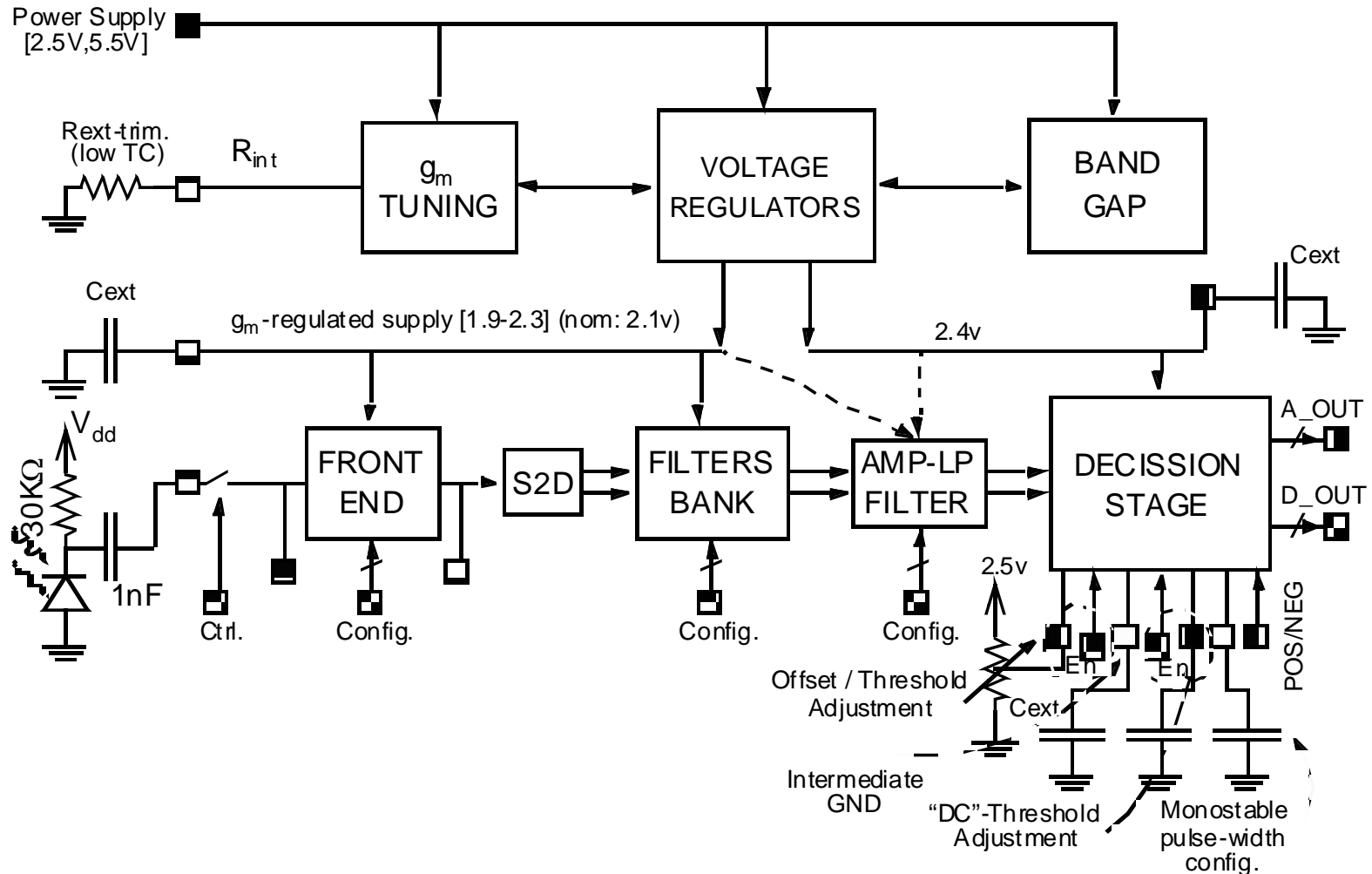
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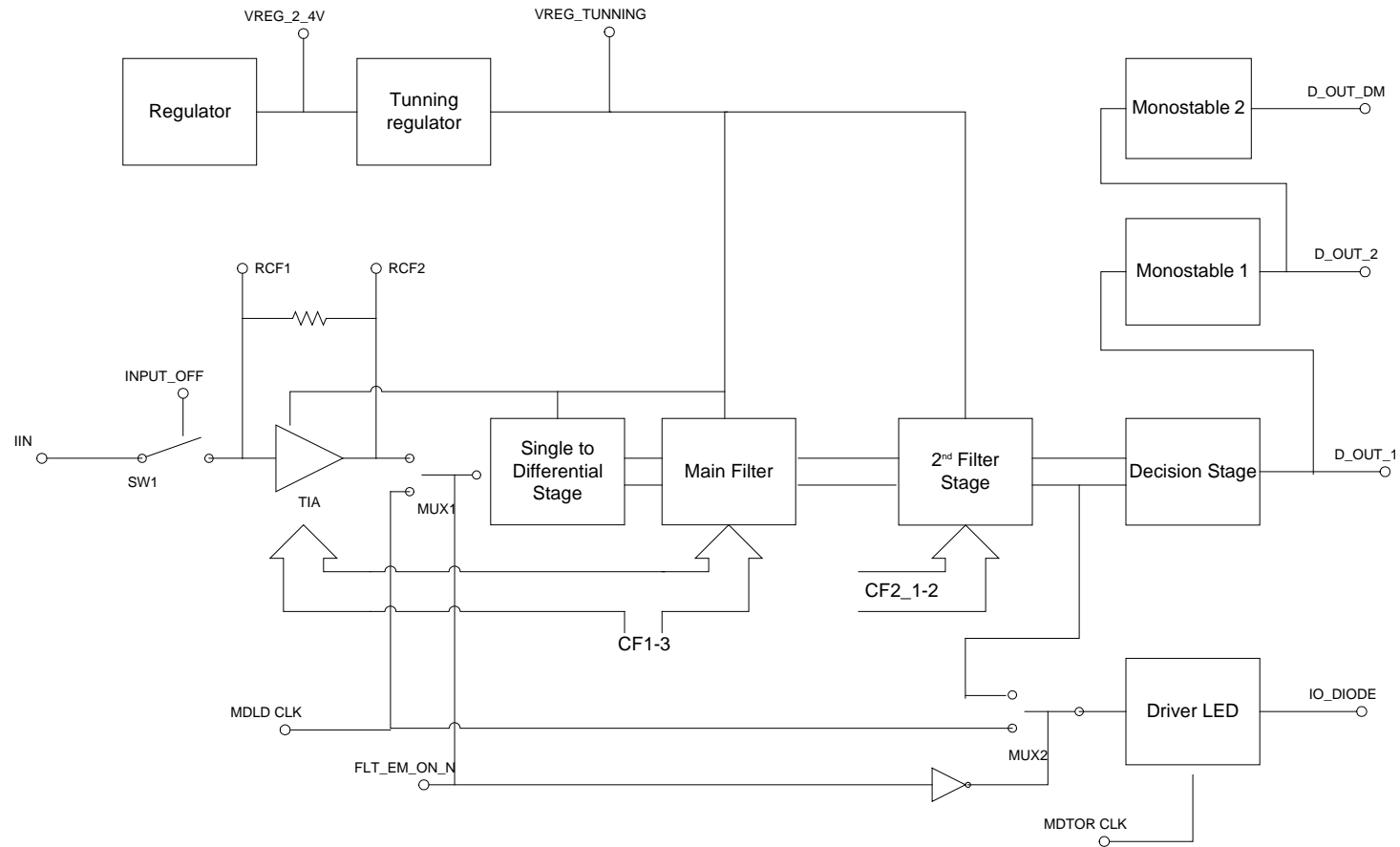
Motivation

- Digital transceiver for diffuse-light intra-satellite asynchronous optical communications
- Baseband and subcarrier-modulation transmissions
- Technology: Austriamicrosystems (AMS) 0.35 μ m CMOS
- TID tolerance: to be maximized. Strict minimum of 50Krad
- SEU and SET LET-thresholds above 70MeV/(mg/cm²)
- Latch-up free behavior up to 70MeV/(mg/cm²)
- Temperature operation range: -90 to +125°C
- Non-operating temperature range: -135 to +150°C

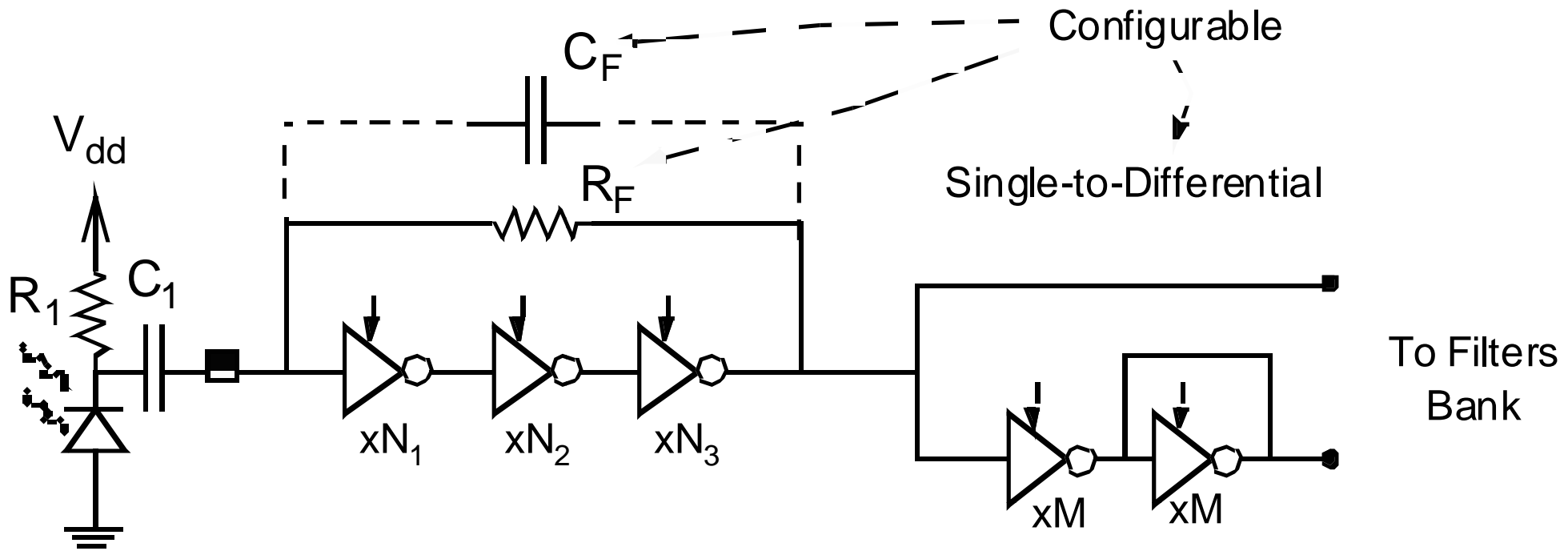
System Description (I)



System Description (II)

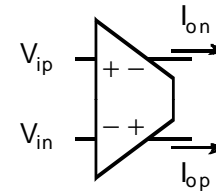


Front End



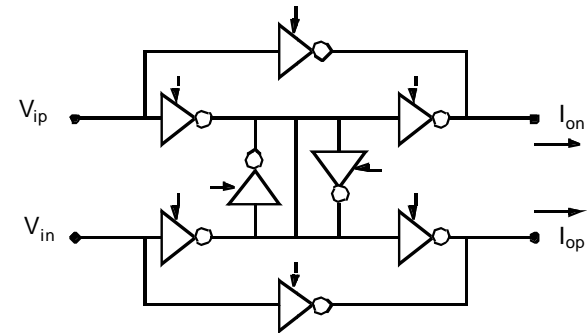
Filter Banks

- Fully-differential Gm-C techniques
- Nauta/Bourdel transconductors, double-poly caps



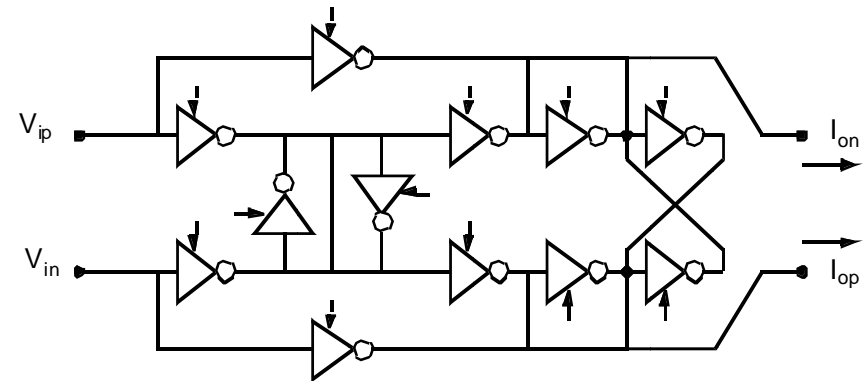
Main filter bank

CFG3	CFG2	CFG1	Type	Band
0	0	0	Low-pass	DC-1MHz
0	0	1	Low-pass	DC-8MHz
0	1	0	Low-pass	DC-20MHz
0	1	1	-	Short (*)
1	0	0	Band-pass	Fc=500kHz, BW=210kHz
1	0	1	Band-pass	Fc=1.65MHz, BW=500kHz
1	1	0	Band-pass	Fc=5.4Mhz, BW=1.5MHz
1	1	1	Band-pass	Fc=18.2MHz, BW=3.3MHz

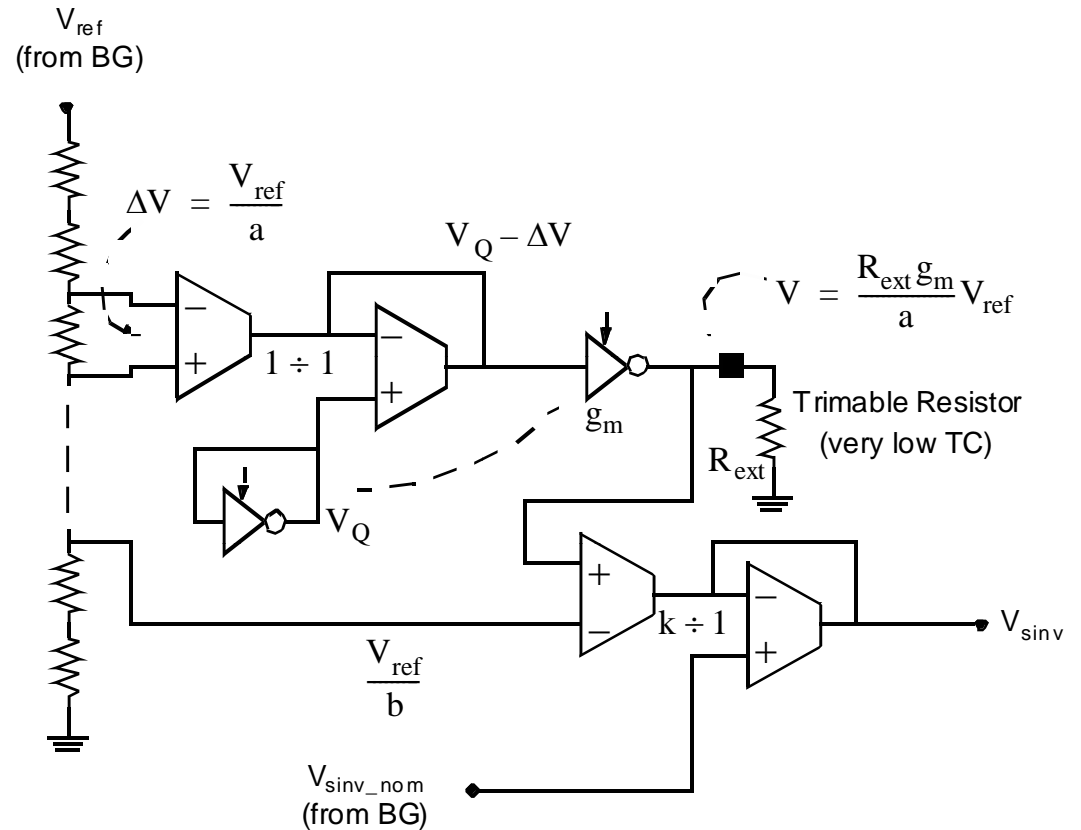
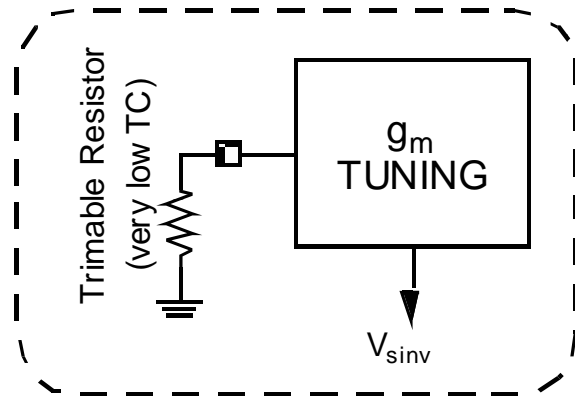


Second filter-bank

CFG2_2	CFG2_1	Band
0	0	2MHz
0	1	10MHz
1	0	20MHz
1	1	Disabled

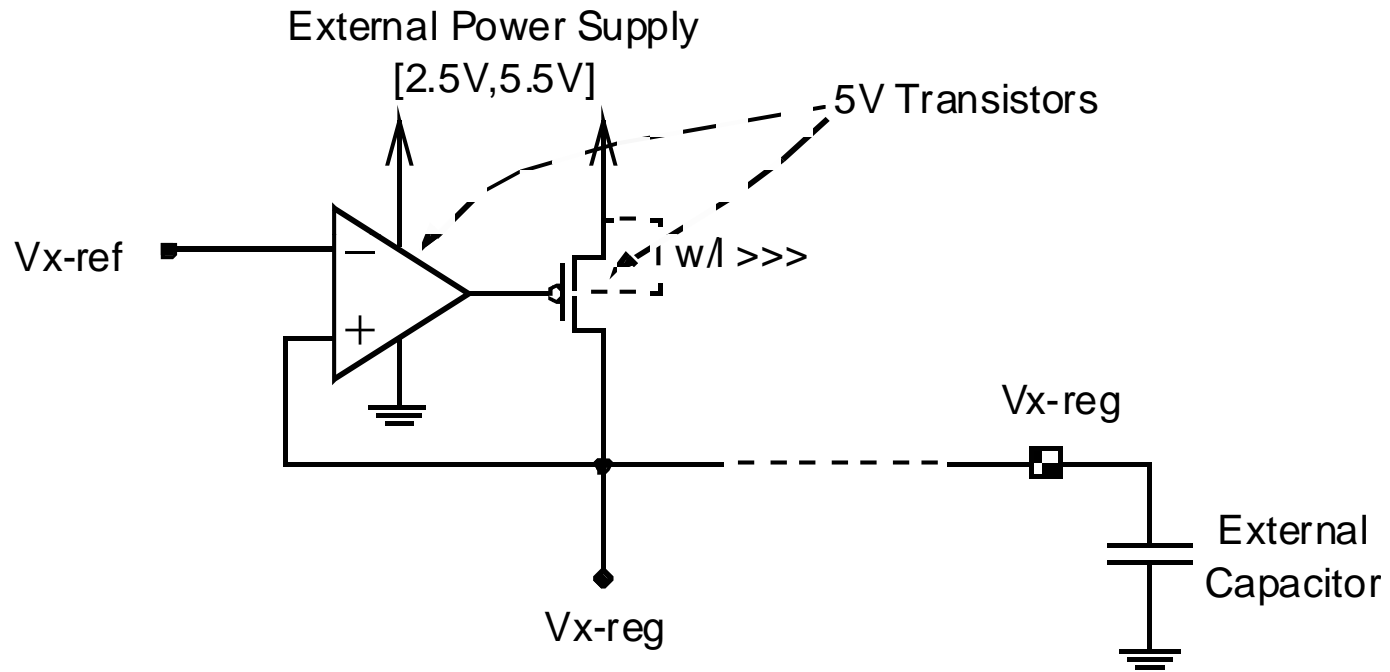


Gm-Tuning

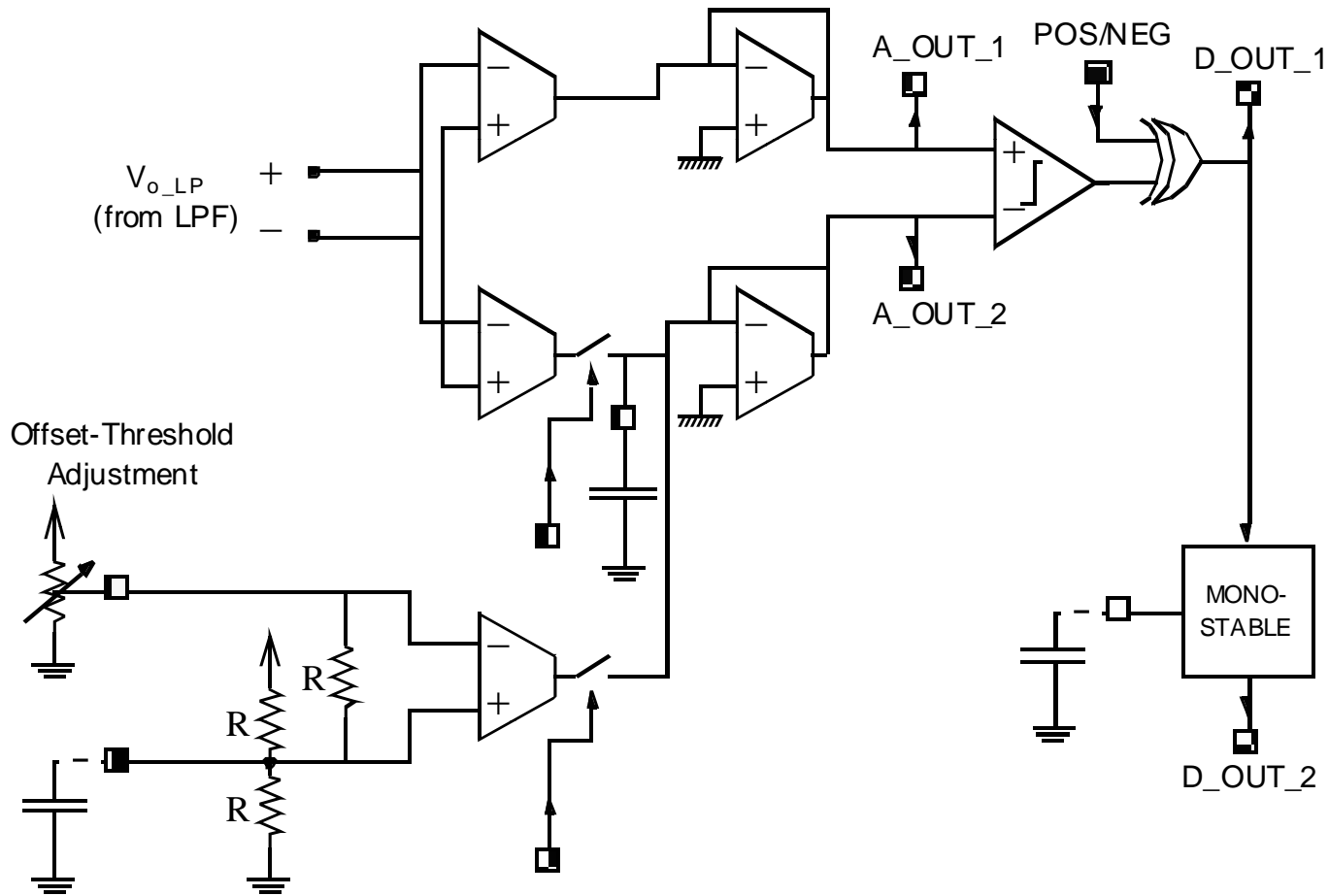


$$\frac{R_{ext} g_m}{a} V_{ref} - \frac{V_{ref}}{b} = 0 \quad \rightarrow \quad R_{ext} g_m = \frac{a}{b}$$

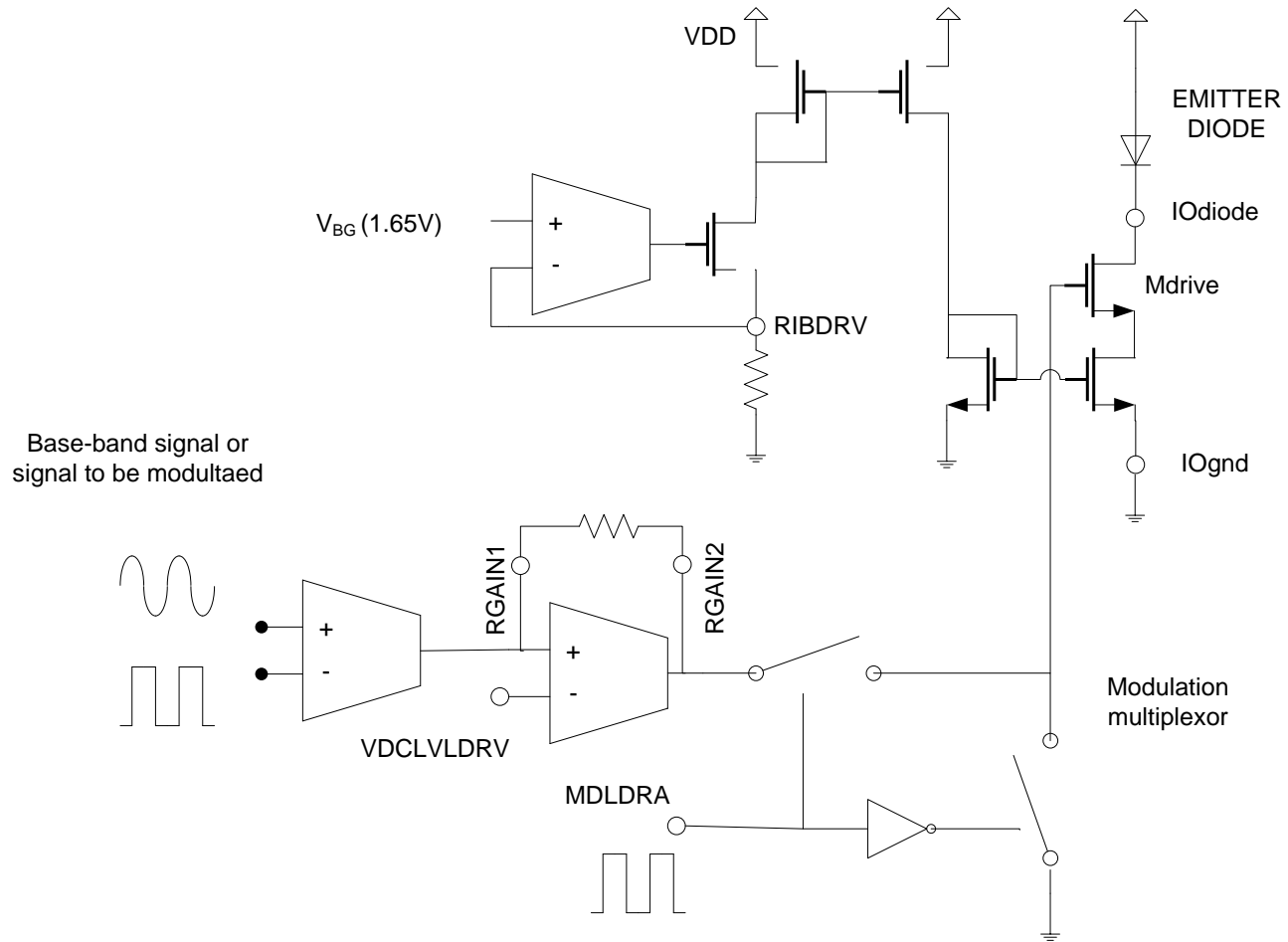
Voltage Regulators



Decision Stage



Driver



Space-Specific Measures

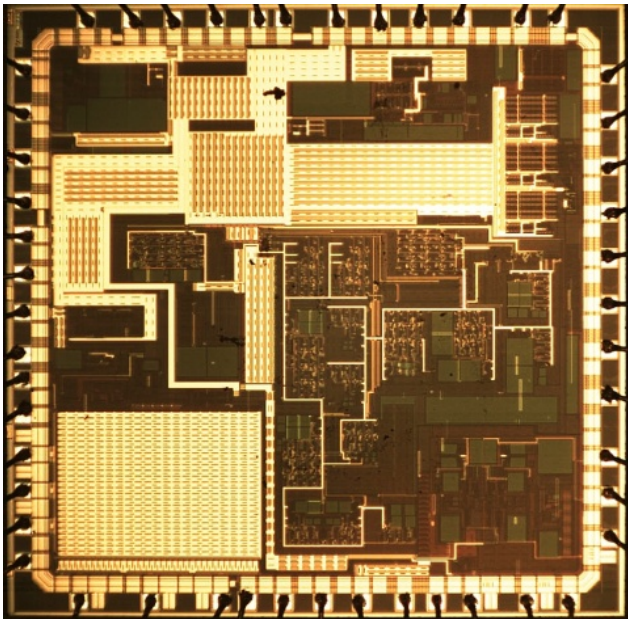
- TID tolerance up to 300Krads, based on tech. charact.
- SEL free up to at least 70MeV/(mg/cm²), based on tech. charact.
- ELT layouts for nmos transistors. Standard layouts for pmos.
- Guard-rings around nmos and pmos transistors.

- Temperature: validation of foundry models in the extended temperature ranges, and electrical simulation

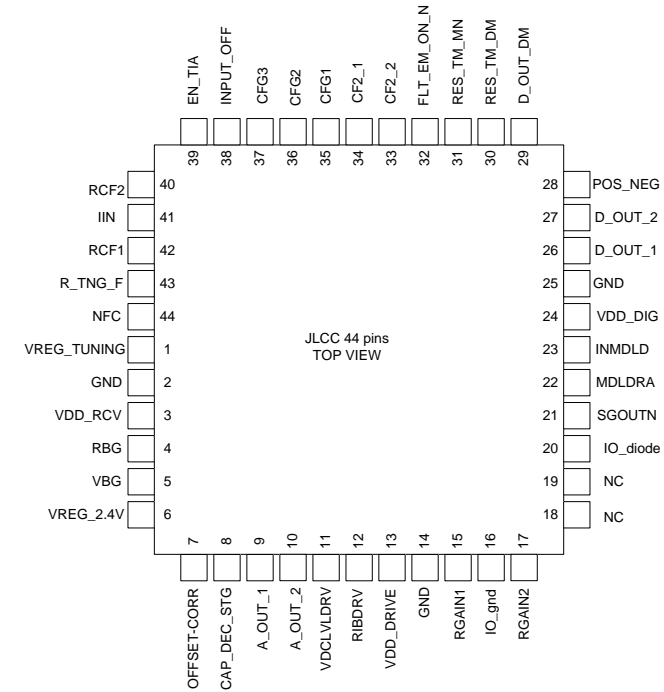
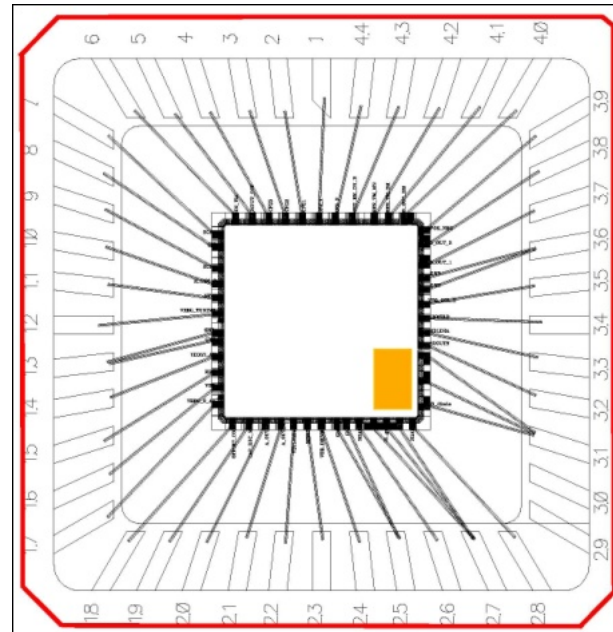
- Amendments in design kit for ELT transistors: symbols, equivalent conventional geometries for electrical simulation, extraction, and LVS.
- p-cells for ELT transistor layout generation

Packaging

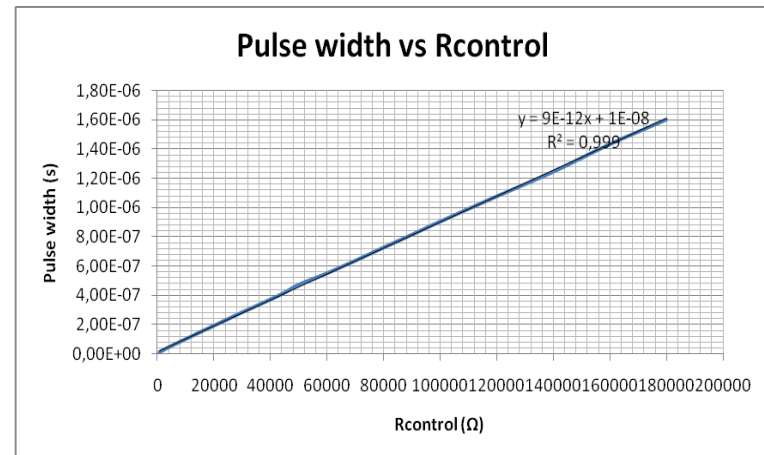
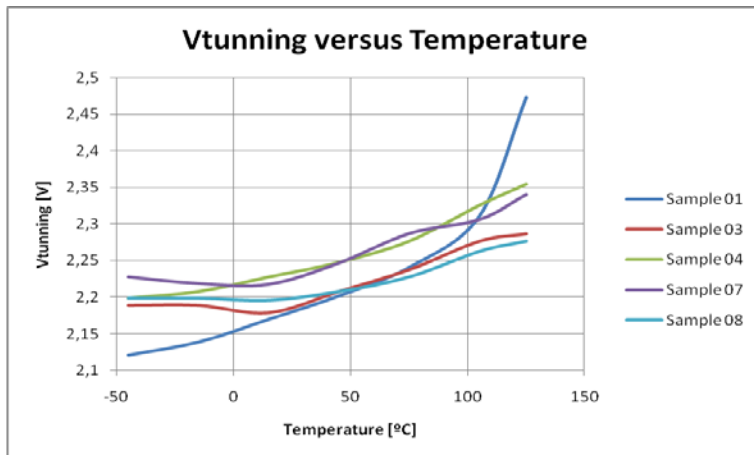
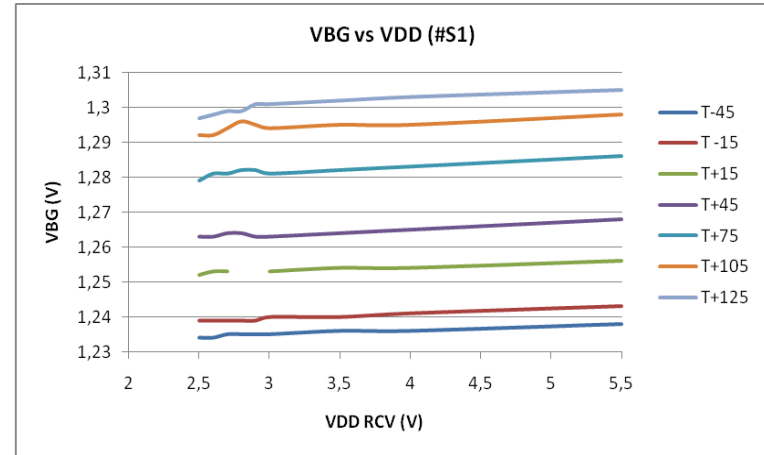
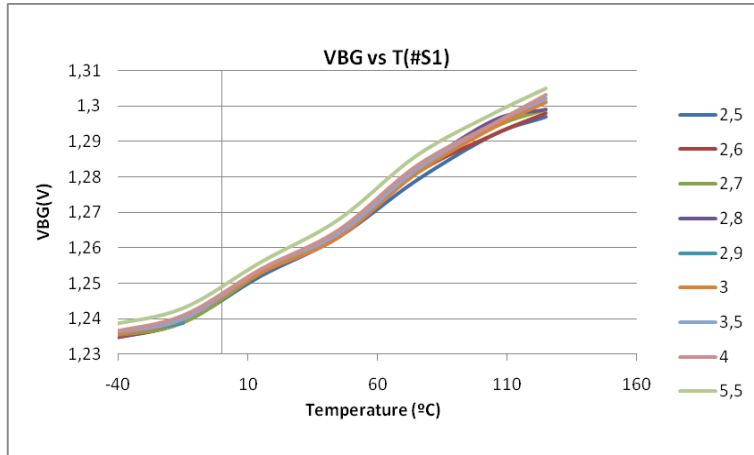
KYOCERA JLCC44 (PB_F86079) ceramic package.



3.5 x 3.5 μm^2

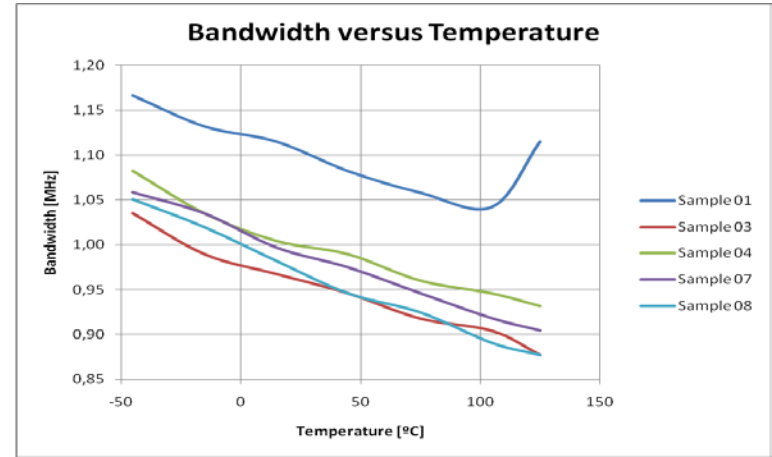
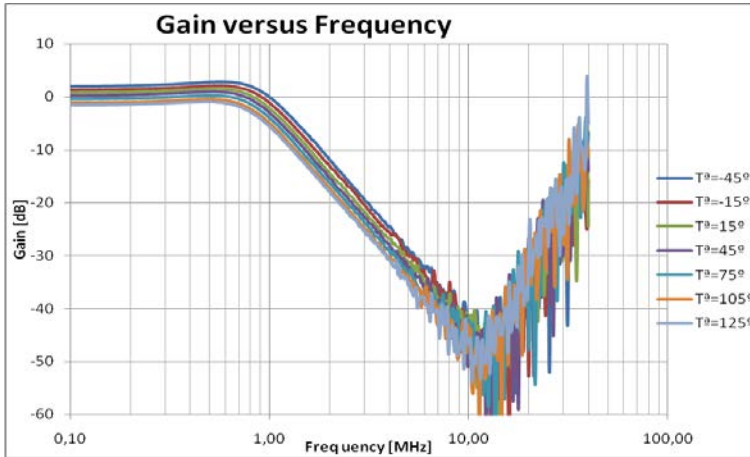


Experimental Results (I)

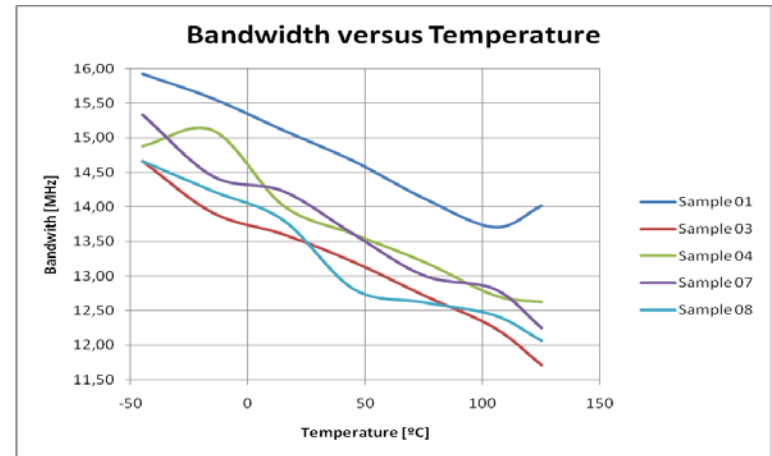
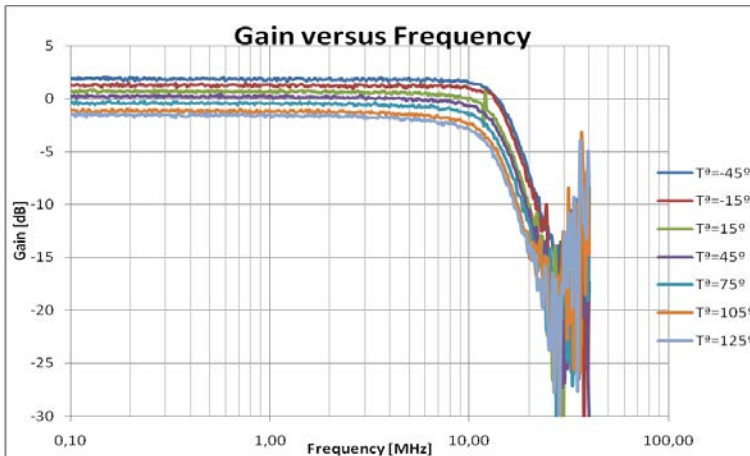


Experimental Results (II)

CFG=000

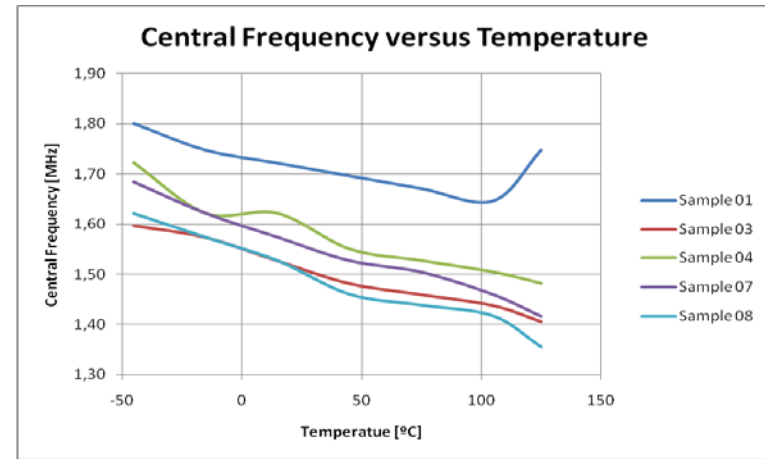
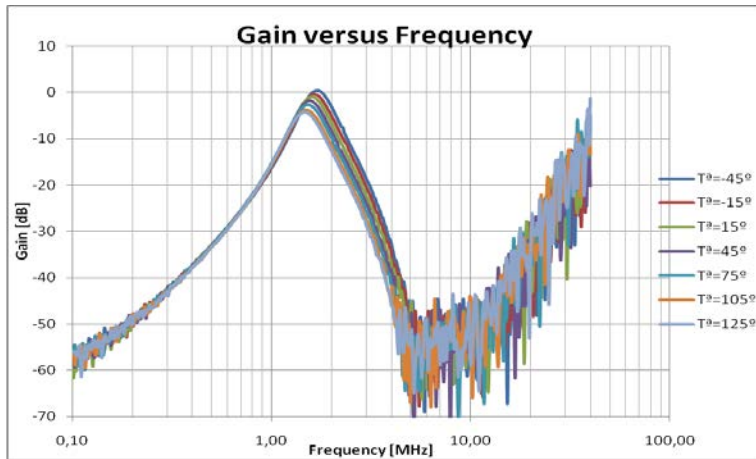


CFG=010

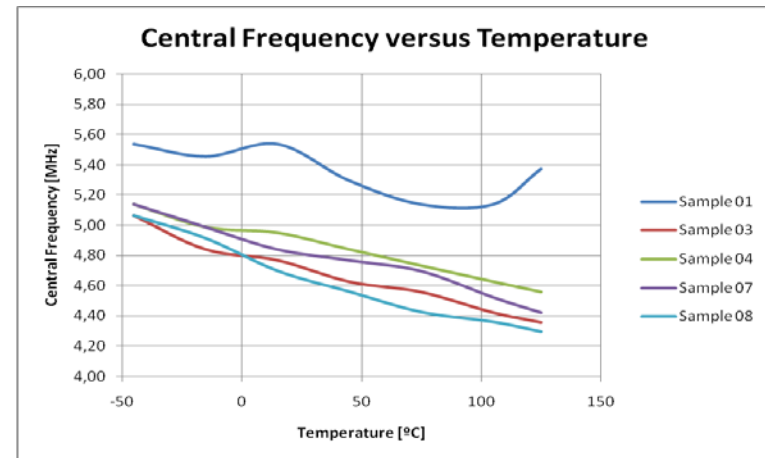
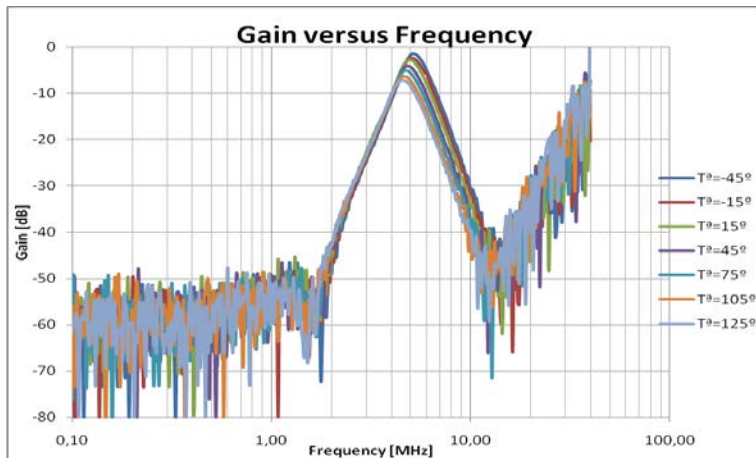


Experimental Results (III)

CFG=101



CFG=110



Experimental Results (IV)

- BER 10^{-8} @500KHz for 100nA amplitude pulse at the TIA input
- BER 10^{-8} @1MHz for 120nA amplitude pulse at the TIA input
- Correct operation of transmitter, although some degradation at high frequency
- Further measurements in progress

On-going & Future Work

- Real-application tests (with photo-diode & LED) to be performed at INTA and IMSE
 - Preliminary qualification by ALTER Technology
 - Irradiation tests planned for next quarter (TID & latch-up)
 - Re-spin for deviations correction:
 - ✓ Band-gap redesign
 - ✓ Independent GNDs at the pad-ring for analog and digital sections
 - ✓ Digital output current reduction (cross-talk)
 - ✓ Emitter low-current section refinement for high frequency improvement
 - Die thickness reduction for QFP packaging
-

- Additional chip being sent to foundry in the coming days: analog front-end bank (ADCs) for tri-axial AMR magnetometer, accelerometer, and temperature measurements. Includes digital section. Digital cells library partially developed.

Acknowledgements

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- People and institutions involved in the characterization of the technology (IMSE, INTA, USC, CNA, UCL) .